

SMD Type 940nm Infrared Emitter

Features

- Small double-end package
- Viewing Angle = ±30°
- High reliability
- Good spectral matching to Si photo detector
- RoHS compliance

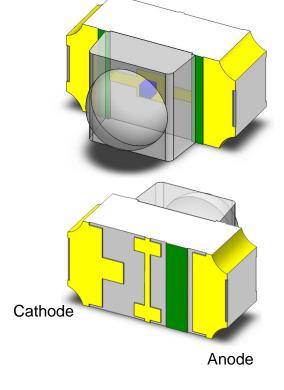
Applications

- Infrared sensor
- Infrared Touch Panel Solutions

Description

The IRP3016W24-G0 is a GaAlAs infrared LED housed in a miniature SMD package. The device has a peak wavelength of 940nm LED spectrally matched with phototransistor or photodiode.

Package Outline



Schematic

Cathode
$$-$$
 Anode



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Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
l _F	Continuous Forward Current	70	mA	
I _{FP}	Peak Forward Current	0.7	Α	1
V _R	Reverse Voltage	5	V	
Topr	Operating Temperature	-40 ~ +85	°C	
T _{stg}	Storage Temperature	-40 ~ +100	°C	
T _{sol}	Soldering Temperature	260	°C	2
PD	Power Dissipation at(or below) 25°CFree Air Temperature	133	mW	
R _{THJA}	Junction to Ambient Thermal Resistance	540	°C/W	

Electro-Optical Characteristics TA = 25°C (unless otherwise specified)

Optical Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Мах	Units	Notes
le	Radiant Intensity	I _F =20mA	4.0	6.4	13.0	mW/sr	
		I _F =70mA	-	22	-	IIIVV/SI	
λр	Peak Wavelength	I _F =20mA	-	940	-	nm	
Δλ	Spectral Bandwidth	I _F =20mA	-	30	-	nm	
θ1/2	Angle of Half Intensity	I _F =20mA	-	±30	-	deg	

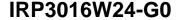
Electrical Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
\/-	Converd Voltage	I _F =20mA	1.1	1.33	1.6	\/	
V _F Forward Voltage	I _F =70mA	1.2	1.57	1.9]		
I _R	Reverse Current	V _R =5V	-	-	10	μA	

Notes:

- 1. I_{FP} Conditions--Pulse Width≤ 100µs and Duty≤ 1%.
- 2. Soldering time≤ 5 seconds.
- 3. le Bin Rank:

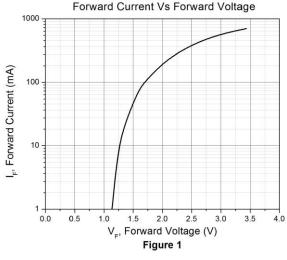
Bin Code	G	Н
Min	4.0	6.5
Max	8.0	13.0

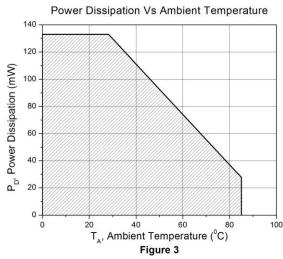


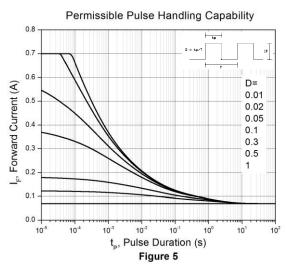


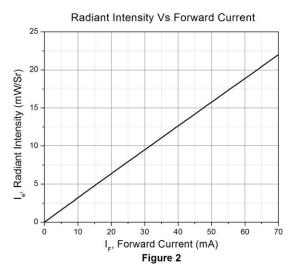
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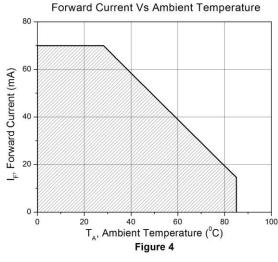
Typical Characteristic Curves

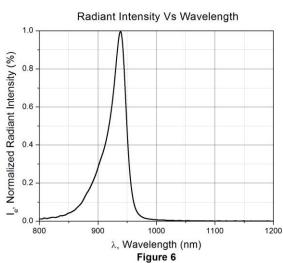








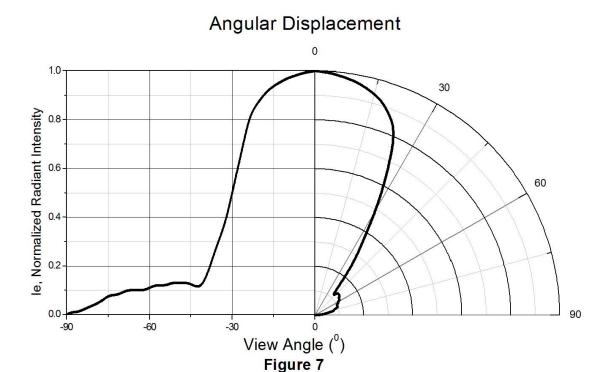






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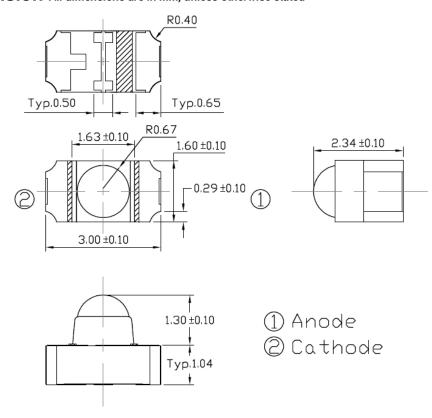
Typical Characteristic Curves



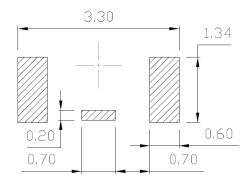


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Package Dimension All dimensions are in mm, unless otherwise stated



Recommended Soldering Mask All dimensions are in mm, unless otherwise stated



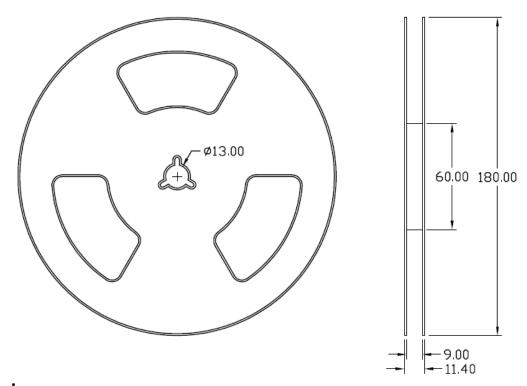
Ordering Information

Part Number	Description	Quantity
IRP3016W24-G0	Tape & Reel	2000 pcs

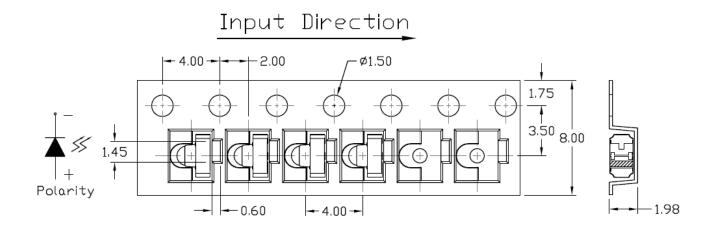


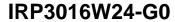
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Reel Dimension All dimensions are in mm, unless otherwise stated



Tape Dimension All dimensions are in mm, unless otherwise stated

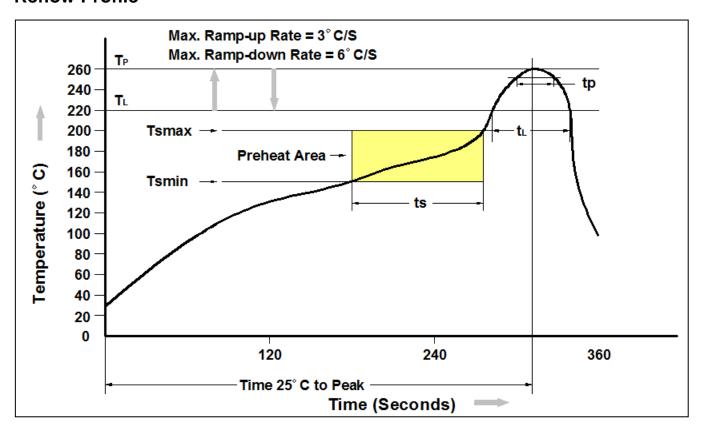






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Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t⊳)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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